

ABSTRACT OF THE DISCLOSURE

The present invention provides a resol-type phenol resin composition which can be cured even in a low temperature range, using a curing accelerator which has no adverse effect on other materials or substances with which the resulting cured article is in contact, or a curing accelerator which requires a small amount of an additive. The composition comprises a resol-type phenol resin (A), an alkali earth metal oxide and/or an alkali earth metal hydroxide (B) (e.g. magnesium oxide, calcium hydroxide, barium hydroxide, etc.), and a salt (C) of a sulfur atom-containing oxo acid and a nitrogen atom-containing base (e.g. ammonium thiosulfate, etc.). This composition is cured at 10 to 110°C.

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